

Supporting Information

Use of decomposable polymer-coated submicron Cu particles with effective additive for production of highly conductive Cu films at low sintering temperature

Yingqiong Yong, Mai Thanh Nguyen, Tetsu Yonezawa,* Masaki Matsubara, Hiroki Tsukamoto, Tengfei Zhang, Shigehito Isobe, and Yuki Nakagawa

Preparation and sintering of PPC-Cu inks

Synthesized PPC-Cu particles (0.3 g, 4.7 mmol) were mixed with α -terpineol (0.3 g, 1.9 mmol, 95%, Kanto, Japan) using conditioning mixer for 18 min and printed on the Al_2O_3 substrates. Then the printed inks were sintered under N_2 for 1 h at 100 °C and 150 °C.

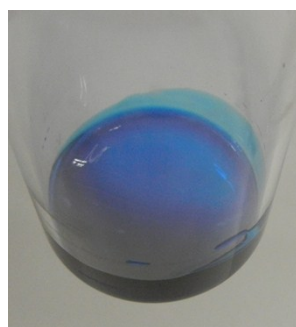


Figure S1. Image of CuF-IPA complex.

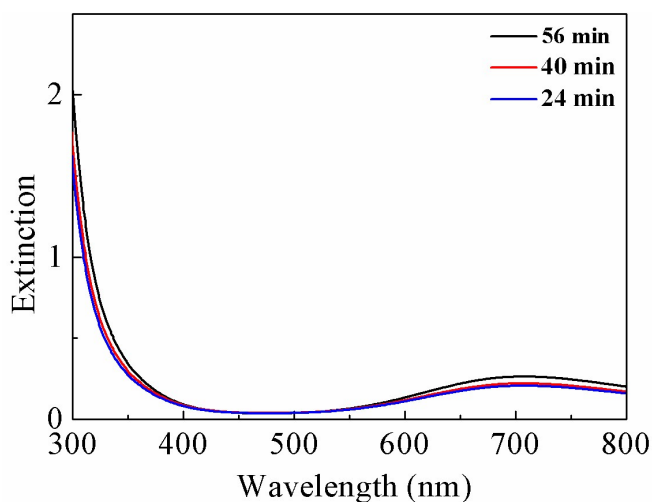


Figure S2. UV-vis extinction spectra of CuF-IPA complex with various mixing time.

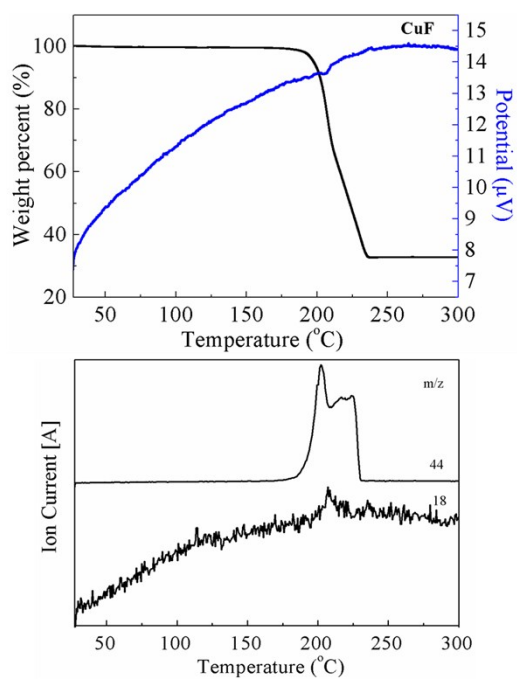


Figure S3. DTA/TGA-MS of CuF. The mass to charge ratios (m/z) detected as pyrolysis product were H₂O (amu=18), and CO₂ (amu=44).

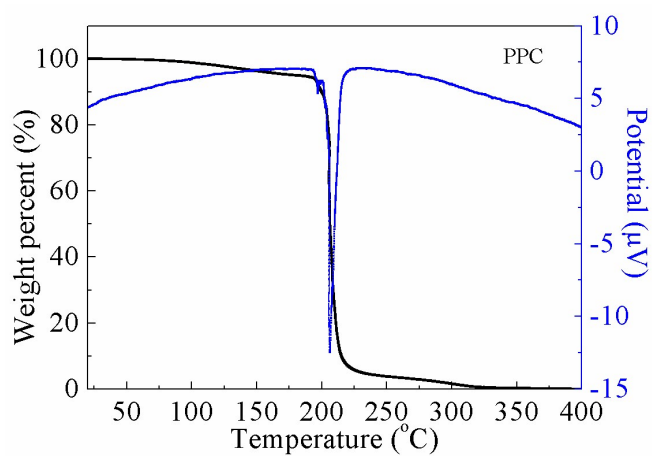


Figure S4. DTA/TGA of PPC under He gas.

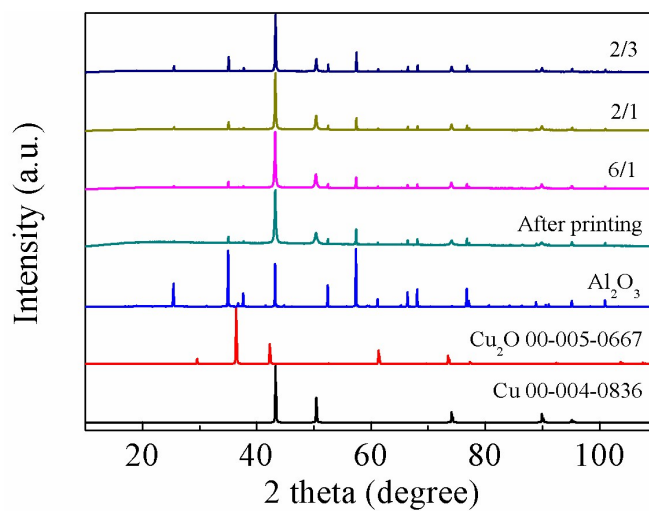


Figure S5. XRD patterns of obtained copper films after sintering at 100 °C for 1 h using PPC-Cu/CuF-IPA 6/1, 2/1 and 2/3 inks.

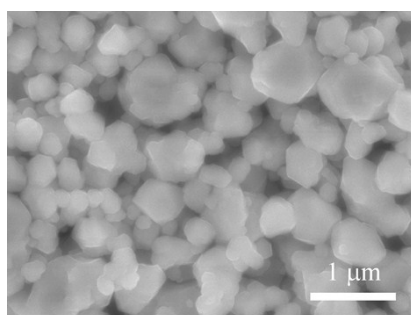


Figure S6. SEM image of obtained copper films using the PPC-Cu/CuF-IPA 2/3 ink after sintering at 100 °C for 2 h.

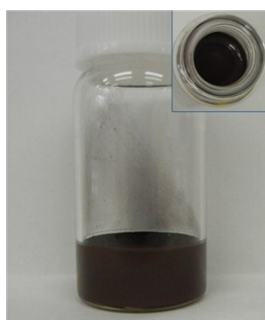


Figure S7. Image of PPC-Cu/CuF-IPA 2/1 ink.

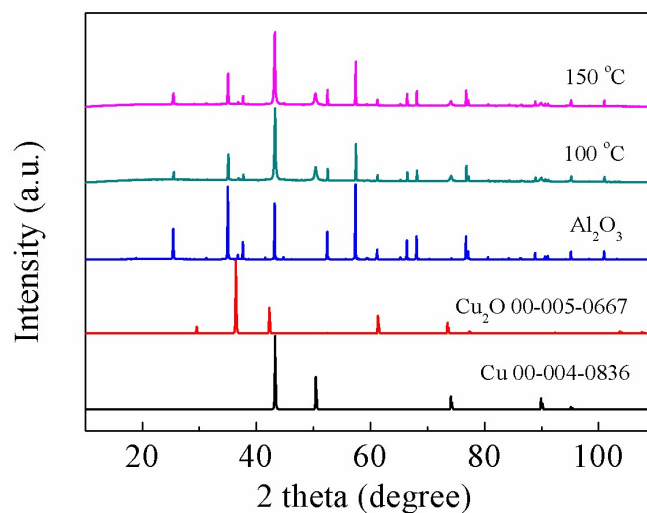


Figure S8. XRD patterns of PPC-Cu particles after sintering at 100 °C and 150 °C under N₂ for 1 h. Reference patterns for Al₂O₃, Cu₂O and Cu are given.

Table S1. Resistivities of the obtained copper films (using only PPC-Cu particles) sintered under N₂ for 1 h

Sintering temperature (°C)	Resistivity (Ω m)
100	Over range
150	Over range

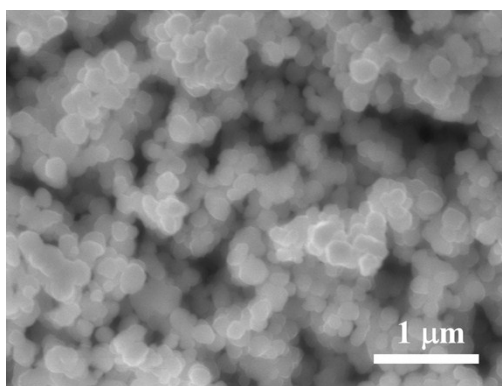


Figure S9. SEM image of the PPC-Cu particles after sintering at 100 °C under N₂ for 1 h.